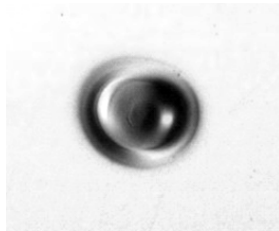
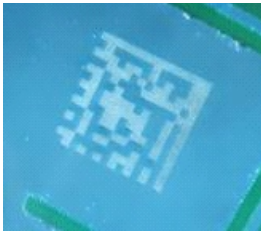
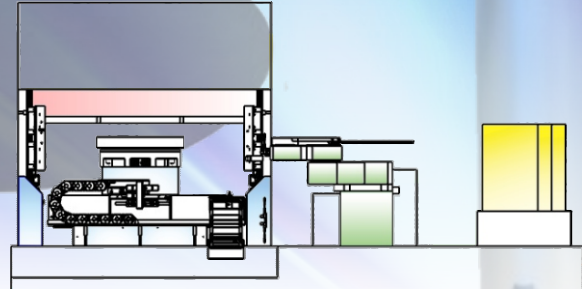


WaferMarking 雷射晶圓雕刻機



高精度規格

- Linear motor XY 線性馬達
- 採用Nd:YVO4 IR 雷射
- 雙Cassette 設計
- OCR reader 辨識 · 載入mapping
- 支援SEMI 圓形字體
- 雕刻品質spot無噴濺



Specifications

Laser System

Wavelength(nm) : 1064nm/IR/TEM00
Positioning Accuracy: $\pm 1\mu\text{m}$
Spot Size: 60~100 μm (custom design)
Lens FOV: 150mm x 150mm

Positioning Mechanism

XY dual axis linear Servo motor system
Close loop Z,Theta Axis
XY Resolution : 0.05 μm
XY Accuracy : $\pm 2\mu\text{m}$
Z Resolution: 0.5 μm
Z Accuracy : $\pm 1\mu\text{m}$
Theta Range: $\pm 5^\circ$

Wafer Handler

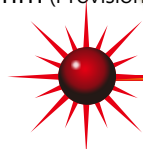
3 axis robot and pre-aligner
6" & 8" Cassette(custom design 12")
Chuck Size: Supports 100-200mm wafers

Inspection and align section

0.5X & 4X Dual CCD

Dimension

Dimension(LxWxH) : 1,650(L)x1,000(W)x1800(H)mm (Provisional assessment)
Weight(kg) : 1,800kgs



LASERTEK TAIWAN CO., LTD.
雷射科技股份有限公司